



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-08-10
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STTH3006DPI	H8UN*945A014	A	Z45A	2016-08-10
Amount		UoM	Unit type	ST ECOPACK Grade
4280.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
Not Applicable	Not Applicable	Not Applicable		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	15.30 - 12.8 - 4.5	2	Through-hole	
Comment	Package: DOP 3 ISOL			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HSUN*945A014					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	19.872	mg	supplier	die	Silicon (Si)	7440-21-3		18.044	mg	908011	4216
				supplier	metallization	Aluminium (Al)	7429-90-5		1.452	mg	73068	339
				supplier	Passivation	Silicon Oxide	7631-86-9		0.123	mg	6190	29
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.006	mg	302	1
				supplier	back side metallization	Gold (Au)	7440-57-5		0.018	mg	905	4
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.086	mg	4328	20
				supplier	polymer die coating	Propimide	proprietary		0.143	mg	7196	33
Leadframe	Copper & its alloys	672.254	mg	supplier	frame alloy	Copper (Cu)	7440-50-8		671.379	mg	998698	156864
				supplier	frame alloy	Iron(Fe)	7439-89-6		0.673	mg	1002	157
				supplier	frame coating	Phosphorus (P)	12185-10-3		0.202	mg	300	48
Heatsink	Copper & its alloys	2376.418	mg	supplier	frame alloy	Copper (Cu)	7440-50-8		2373.327	mg	998699	554516
				supplier	frame alloy	Iron(Fe)	7439-89-6		2.377	mg	1001	555
				supplier	frame coating	Phosphorus (P)	12185-10-3		0.714	mg	300	167
Ceramic	Ceramics / Glass	19.772	mg	supplier	Ceramic	Ceramic	proprietary	19.772	mg	1000000	4620	
Die attach	Other Organic Materials	74.540	mg	JIG - R	soft solder	Lead(Pb)	7439-92-1	7a-Lead in high me	69.695	mg	935001	16284
				supplier	soft solder	Silver(Ag)	7440-22-4		1.118	mg	14999	261
				supplier	soft solder	Tin(Sn)	7440-31-5		3.727	mg	50000	871
Bonding wire	Aluminum & its alloys	21.749	mg	supplier	Bonding wire	Aluminium (Al)	7429-90-5		21.749	mg	1000000	5082
Encapsulation	Other Organic materials	1067.694	mg	supplier	Molding Compound	Silica, vitreous	60676-86-0		811.447	mg	760000	189590
				supplier	Molding Compound	Phenol resin	9003-35-4		64.062	mg	60000	14968
				supplier	Molding Compound	Carbon black	1333-86-4		8.541	mg	8000	1996
				supplier	Molding Compound	Epoxy Cresol Novolak	29690-82-2		108.905	mg	102000	25445
				supplier	Molding Compound	Metal hydroxide	21645-51-2		21.354	mg	20000	4989
			mg	supplier	Molding Compound	Others	Proprietary		53.385	mg	50000	12473
Finishing	Other inorganic materials	27.701	mg	supplier	Connection coating	Tin(Sn)	7440-31-5		27.701	mg	1000000	6472